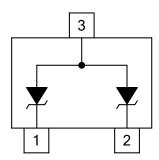


Description

SET23A12L02-E18 is designed to protect components which are connected to data and transmission lines from voltage surges caused by electrostatic discharge (ESD), electrical fast transients (EFT) and lightning. TVS diodes are characterized by their high surge capability, low operating and clamping voltages, and fast response time. This makes them ideal for use as board level protection of sensitive semiconductor components.

The low profile SOT-23 package allows flexibility in the design of crowded circuit boards.



Features

- IEC61000-4-2 ESD 30KV Air, 30KV contact compliance
- Protects one bidirectional line or two unidirectional lines
- Working voltage: 12V
- · Low leakage current
- Low operating and clamping voltages
- Solder reflow temperature: Pure Tin-Sn, 260~270°C

Applications

- · Cellular handsets and accessories
- Personal digital assistants (PDA's)
- Portable instrumentation
- Set Top Box (STB)
- Servers, notebook, and desktop PC
- Wireless bus protection
- RS-232, RS-422, RS-423 protection



Maximum Ratings

Rating	Symbol	Value	Unit	
Peak pulse power (tp=8/20µs waveform)	P _{PP}	500	W	
ESD voltage (Contact discharge)	.,	±30	kV	
ESD voltage (Air discharge)	V_{ESD}	±30		
Storage & operating temperature range	T _{STG} ,T _J	-55~+150	$^{\circ}$	

Electrical Characteristics (T_J=25℃)

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Reverse stand-off voltage	V _{RWM}				12	V
Reverse breakdown voltage	V_{BR}	I _{BR} =1mA	13.3			V
Reverse leakage current	I _R	V _R =12V Each I/O pin			1	μA
Clamping voltage (tp=8/20µs)	Vc	I _{PP} =1A			19	V
Clamping voltage (tp=8/20µs)	Vc	I _{PP} =18A			27	V
Off state junction capacitance	Сл	0Vdc,f=1MHz Between I/O pins and GND		100		pF



Typical Characteristics Curves

Figure 1. Power Derating Curve

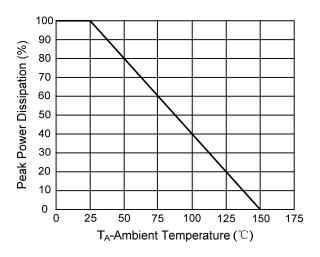


Figure 3. Forward Voltage vs. Forward Current

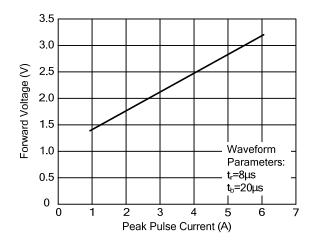


Figure 2. Pulse Waveforms

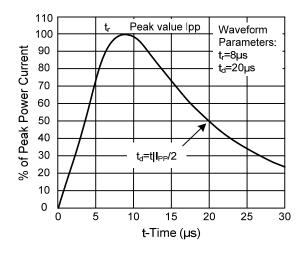
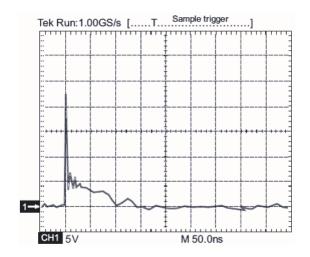


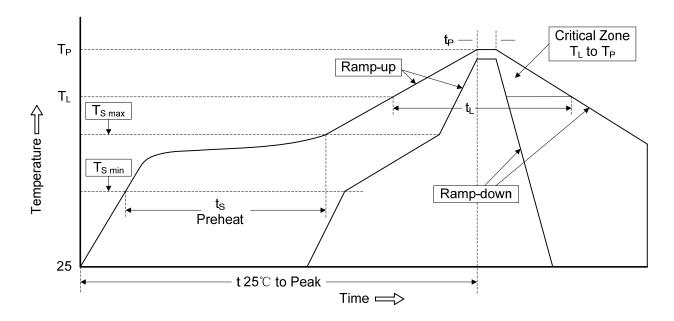
Figure 4. ESD Clamping(8kV Contact IEC61000-4-2)





Recommended Soldering Conditions

Reflow Soldering

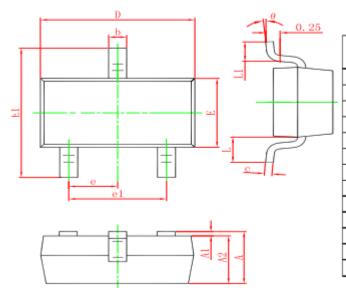


Recommended Conditions

Profile Feature	Pb-Free Assembly		
Average ramp-up rate (T _L to T _P)	3°C/second max.		
Preheat			
-Temperature Min (T _{S min})	150℃		
-Temperature Max (T _{S max})	200℃		
-Time (min to max) (ts)	60-180 seconds		
T _{S max} to T _L			
-Ramp-up Rate	3°C/second max.		
Time maintained above:			
-Temperature (T∟)	217℃		
-Time (t∟)	60-150 seconds		
Peak Temperature (T _P)	260℃		
Time within 5℃ of actual Peak Temperature (t _P)	20-40 seconds		
Ramp-down Rate	6℃/second max.		
Time 25℃ to Peak Temperature	8 minutes max.		

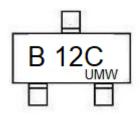


SOT-23 PACKAGE OUTLINE DIMENSIONS



Cumbal	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
E	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950	TYP.	0.037 TYP.		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF.		0.022 REF.		
L1	0.300	0.500	0.012	0.020	
А	0°	8°	0°	8°	

Marking



Ordering information

Order code	Package	Baseqty	Deliverymode
UMW SET23A12L02-E18	SOT-23	3000	Tape and reel

单击下面可查看定价,库存,交付和生命周期等信息

>>UMW(友台半导体)